

FLIP CHIP ARRAY

APPLICATIONS

- ✓ Cellular Phones
- ✓ Personal Digital Assistant (PDA)
- ✓ Ground Positioning System (GPS)
- ✓ SMART & PCMCIA Cards

IEC COMPATIBILITY (EN61000-4)

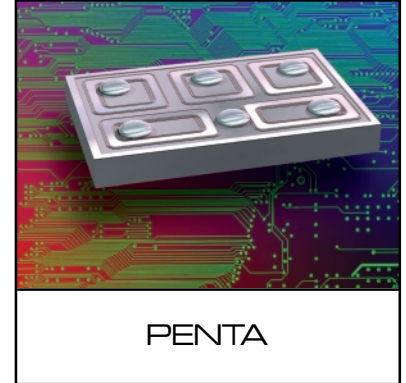
- ✓ 61000-4-2 (ESD): Air - 15kV, Contact - 8kV
- ✓ 61000-4-4 (EFT): 40A - 5/50ns
- ✓ 61000-4-5 (Surge): 24A, 8/20 μ s - Level 2(Line-Gnd) & Level 3(Line-Line)

FEATURES

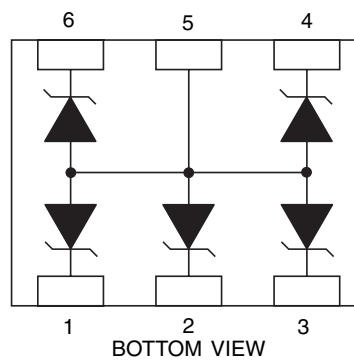
- ✓ ESD Protection > 25 kilovolts
- ✓ 250 Watts Peak Pulse Power per Line ($t_p = 8/20\mu$ s)
- ✓ Protects up to Five(5) Unidirectional & Four (4) Bidirectional Lines

MECHANICAL CHARACTERISTICS

- ✓ Weight 0.73 milligrams (Approximate)
- ✓ Flammability Rating UL 94V-0
- ✓ 8mm Plastic & Paper Tape and Reel Per EIA Standard 481
- ✓ Device Marking On Reel
- ✓ Top Contacts: Solder Bump 0.004" in Height (Nominal)



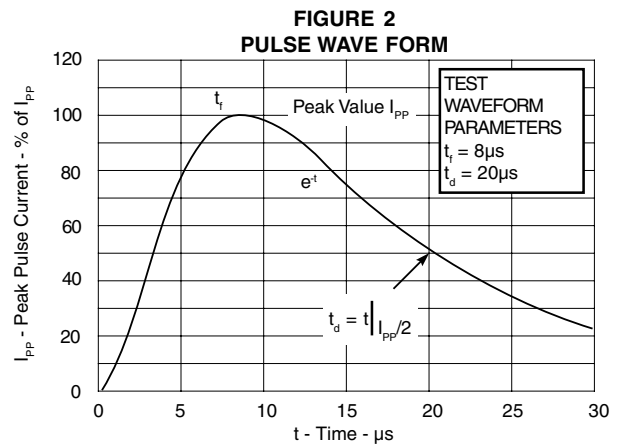
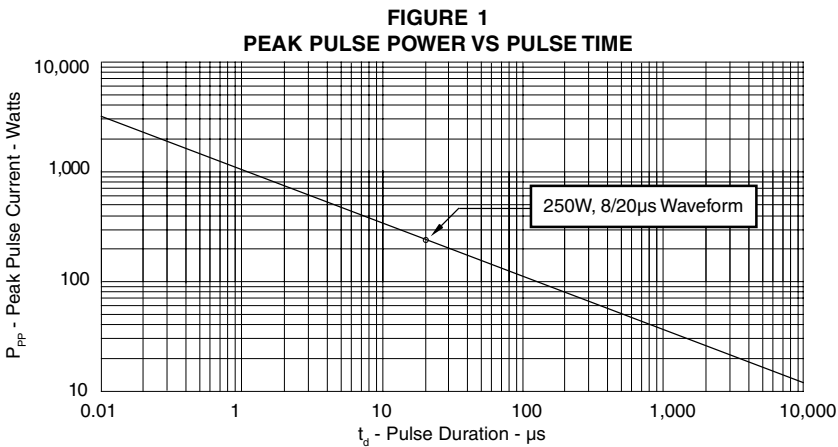
PENTA

PIN CONFIGURATION

DEVICE CHARACTERISTICS

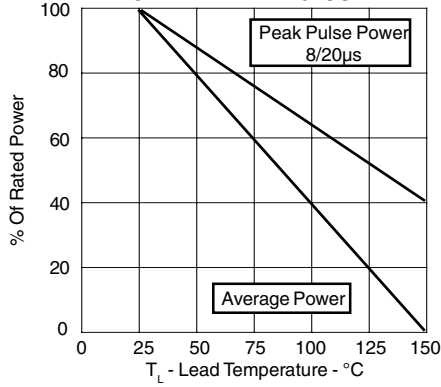
MAXIMUM RATINGS @ 25°C Unless Otherwise Specified			
PARAMETER	SYMBOL	VALUE	UNITS
Peak Pulse Power ($t_p = 8/20\mu s$) - See Figure 1	P_{PP}	250	Watts
Operating Temperature	T_J	-55°C to 150°C	°C
Storage Temperature	T_{STG}	-55°C to 150°C	°C

ELECTRICAL CHARACTERISTICS PER LINE @ 25°C Unless Otherwise Specified						
PART NUMBER	RATED STAND-OFF VOLTAGE	MINIMUM BREAKDOWN VOLTAGE	MAXIMUM CLAMPING VOLTAGE (See Fig. 2)	MAXIMUM CLAMPING VOLTAGE (See Fig. 2)	MAXIMUM LEAKAGE CURRENT	TYPICAL CAPACITANCE
	V_{WM} VOLTS	@ 1mA $V_{(BR)}$ VOLTS	@ $I_p = 5A$ V_c VOLTS	@ 8/20 μs $V_c @ I_{PP}$	@ V_{WM} I_D μA	@ 0V, 1 MHz C_i pF
SFC05-5	5.0	6.0	9.5	11.0V @ 24A	10	150

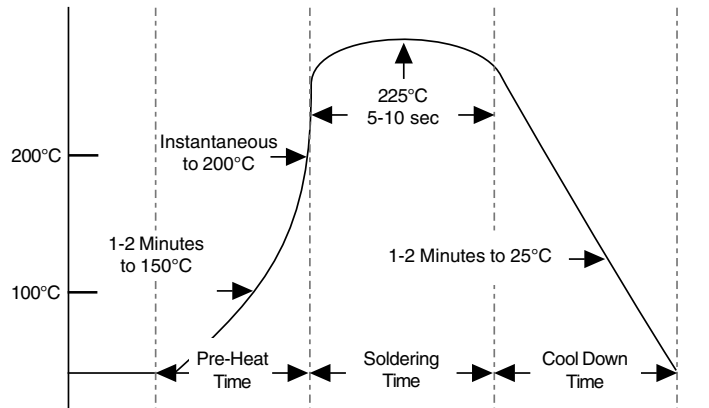


GRAPHS

**FIGURE 3
POWER DERATING CURVE**

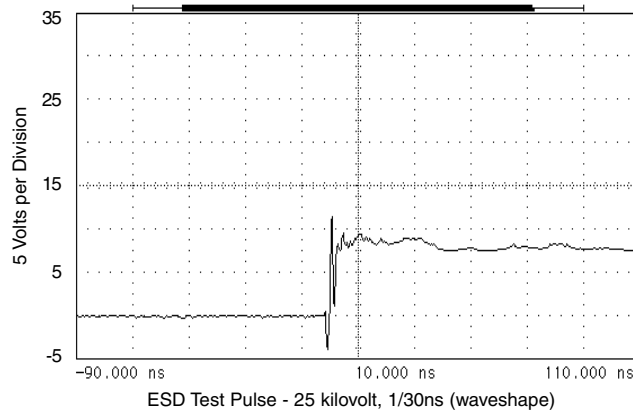


**FIGURE 4
REFLOW SOLDER PROFILE**

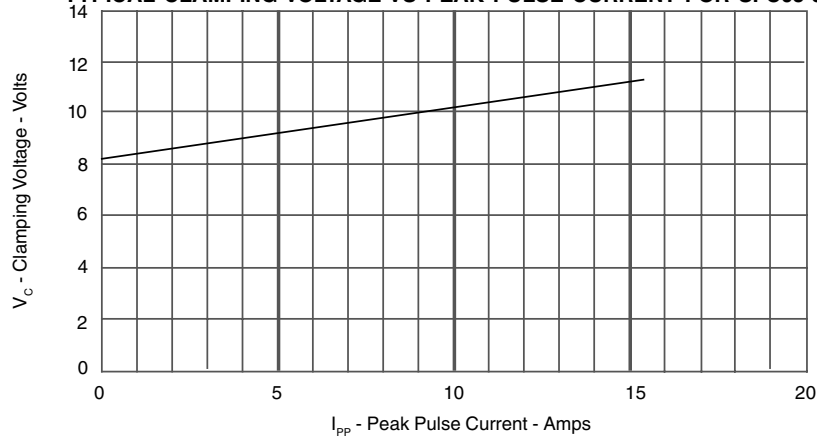


Note: This reflow profile does not take into account the printed circuit board (PCB) material heating time. Additional time may be required for the preheat time and cool down time upon the PCB or board material.

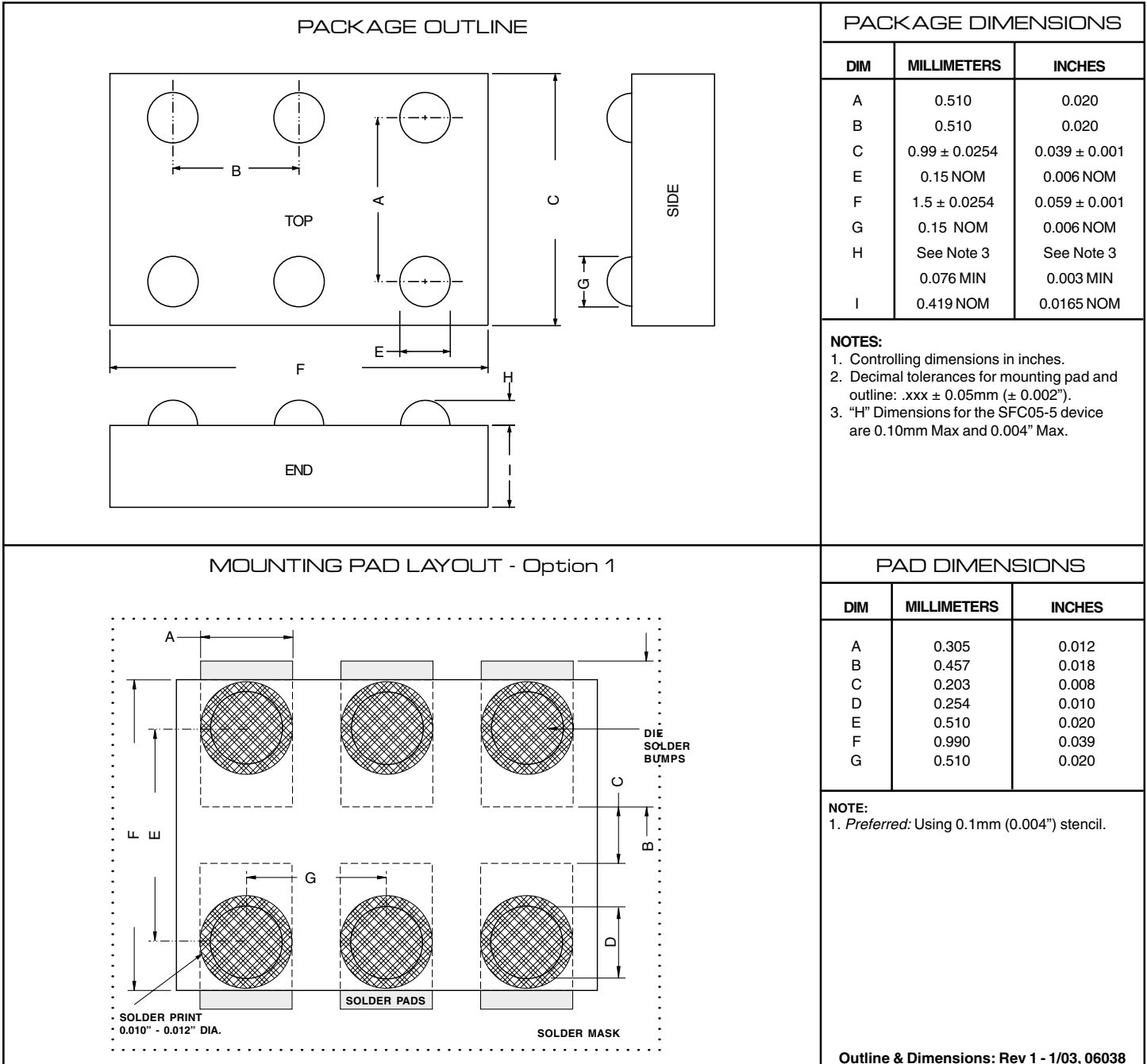
**FIGURE 5
OVERSHOOT & CLAMPING VOLTAGE FOR SFC05-5**



**FIGURE 6
TYPICAL CLAMPING VOLTAGE VS PEAK PULSE CURRENT FOR SFC05-5**

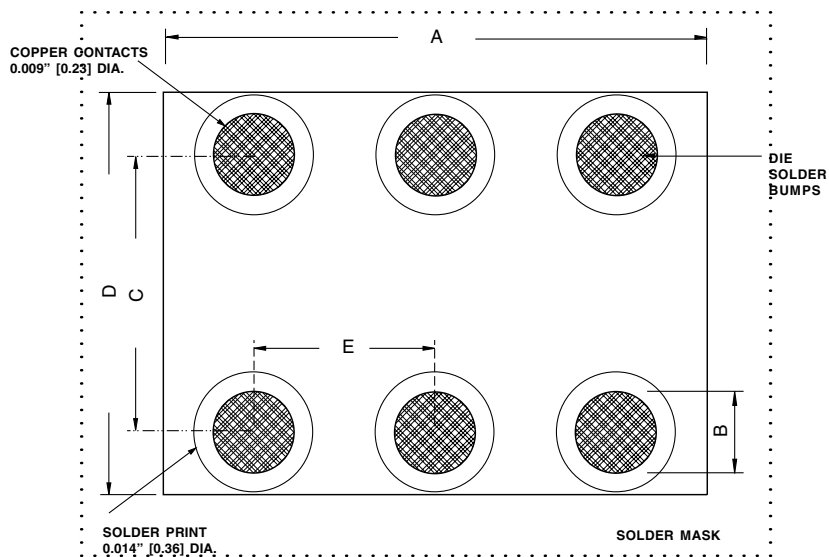


PACKAGE OUTLINE & DIMENSIONS



PACKAGE OUTLINE & DIMENSIONS

MOUNTING PAD LAYOUT - Option 2



PACKAGE DIMENSIONS

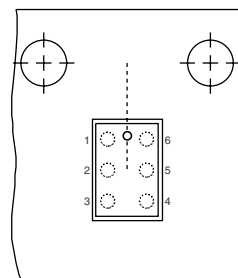
DIM	MILLIMETERS	INCHES
A	1.5 NOM	0.059
B	0.152 NOM	0.006 NOM
C	0.510	0.020
D	0.990	0.039
E	0.510	0.020

NOTES:

1. Controlling dimensions in inches.
2. Decimal tolerances for mounting pad and outline: .xxx ± 0.05mm (± 0.002").
3. Preferred: Using 0.1mm (0.004") stencil.

Outline & Dimensions: Rev 0 - 10/02, 06039

TAPE & REEL ORIENTATION



NOTE:

1. Top view of tape. Solder bumps are face down in tape package.

TAPE & REEL ORDERING NOMENCLATURE

1. Surface mount product is taped and reeled in accordance with EIA 481.
2. 8mm Plastic Tape: 7 Inch Reels - 5,000 pieces per reel. Ordering Suffix: -T75-1 (i.e., SFC05-5-T75-1).
3. 8mm Paper Tape: 7 Inch Reels - 5,000 pieces per reel. Ordering Suffix: -T75-2 (i.e., SFC05-5-T75-2).

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